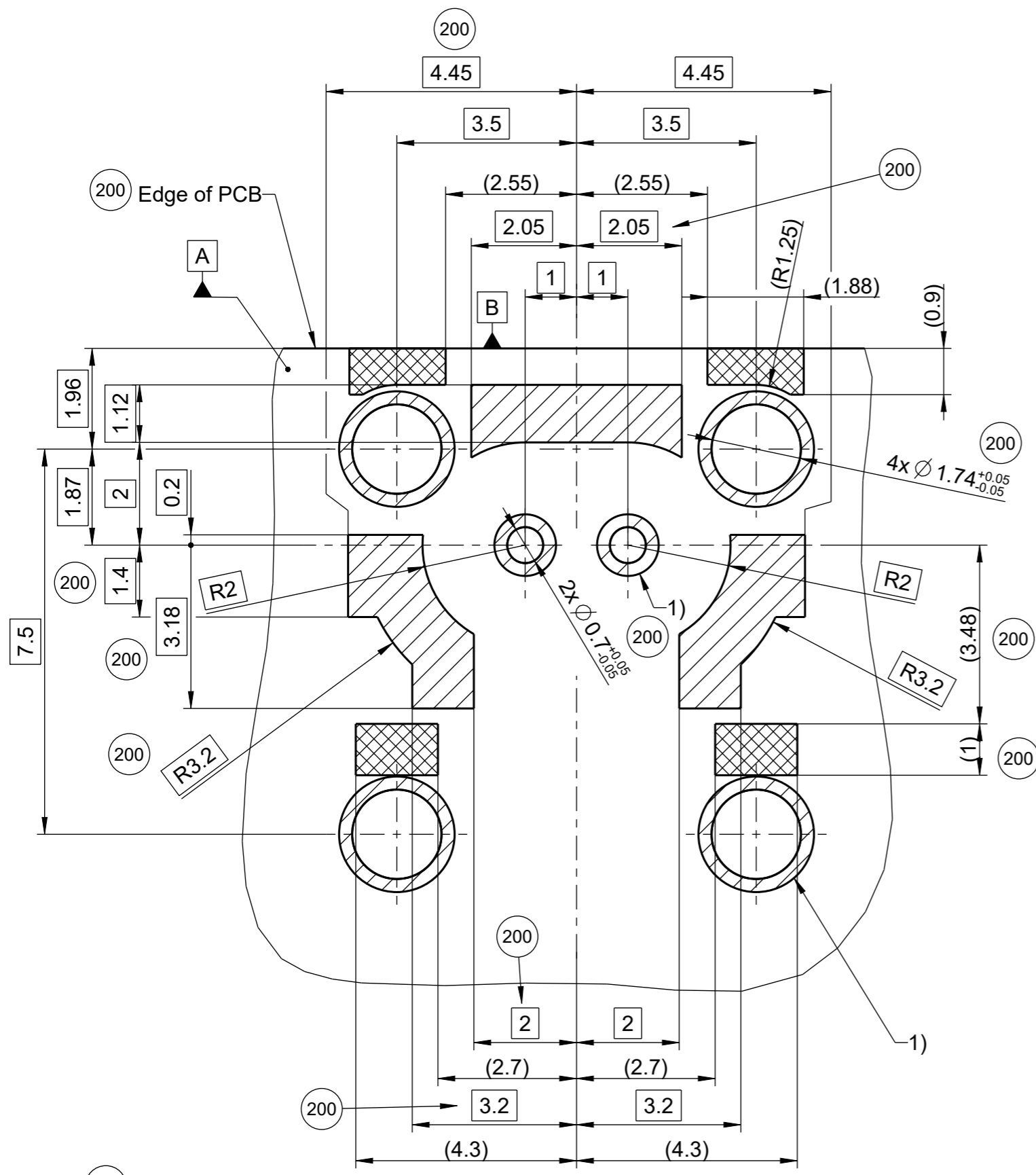


**NUR FUER MUSTERFERTIGUNG  
ONLY FOR SAMPLE PRODUCTION**



- 1) Pad width min. 0.2 mm
- 2) Thickness of soldering paste min. 0.1 mm
- 3) All through holes plated inclusive pads on the backside

- 4) All through holes 

⊕	0.2	A	B
⊕	∅ 0.05	M	A
- 5) Solder area and keep out area 

	0.2	A	C-C
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Solder area  
 Keep out area, free of solder, no routing underneath

Rev.	Change
200	-Increased through hole diameter for outer contact to 1.74 mm -Slight change to the solder areas -Changed minimal pad width to 0.2 mm -Replaced pad diameter for inner contact with reference to note 1) -Removed all descriptions in german language -Small text changes for better understanding

<b>Rosenberger</b>	general tolerance ISO 2768 mH	RN 006-01 dimensions <0,5 and symmetry	scale: 10:1 ( )	weight[g]: 2.716 surface[mm <sup>2</sup> ]: 534.3
	<b>vertraulich / confidential</b>		material:	
		date	name	title: <b>Leiterplatten-Layout PCB-Layout</b>
		drawn	20.11.2018 M_Kolbe	
		check	20.03.2020 F_Schnitznb	
		appr.	02.04.2020 S_Loeffelhol	drawing-no.: MB_780
		dimensioning incl. plating		
200	20-0316	M_Kolbe	16.03.2020	Size ISO 14405 (E) Tolerancing ISO 8015
100	18-m771	M_Kolbe	06.12.2018	drawing-no.: MB_780
rev. change-no		name date		sheet: 1 of: 1
				remarks: MB_633

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 PD\_FB\_01  
 -METRIC-  
 ISO-Projektion Methode 1

The stated dimensions are only recommendations.  
 A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.  
 Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.  
 In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.